

What is claimed is:

1. An electronic device comprising:
 - a substrate on which an interconnect pattern is formed;
 - 5 a chip component having a first surface on which a pad is formed and a second surface opposite to the first surface, the chip component being mounted in such a manner that the second surface faces the substrate;
 - a metal layer formed on the pad, the metal layer being less oxidizable than the pad;
- 10 an insulating section formed adjacent to the chip component; and
- an interconnect which is formed to extend from above the metal layer, over the insulating section and to above the interconnect pattern.
2. The electronic device as defined by claim 1,
- 15 wherein the insulating section is formed of resin.
3. The electronic device as defined by claim 1,
wherein the insulating section has an inclined surface descending in an outward direction from the chip component.
- 20 4. The electronic device as defined by claim 2,
wherein the insulating section has an inclined surface descending in an outward direction from the chip component.
- 25 5. A method of manufacturing an electronic device, the method comprising :
mounting a chip component having a pad on a substrate on which an interconnect pattern is formed, in such a manner that a second surface faces the

substrate, the pad being formed on a first surface and the second surface being opposite to the first surface;

forming a metal layer on the pad, the metal layer being less oxidizable than the pad;

5 forming an insulating section adjacent to the chip component; and

forming an interconnect in such a manner as to extend from above the metal layer, over the insulating section and to above the interconnect pattern.

6. The method of manufacturing an electronic device as defined by claim 5,

10 wherein the interconnect is formed of a dispersant including electrically conductive particles.

7. The method of manufacturing an electronic device as defined by claim 6,

15 wherein the step of forming the interconnect includes ejecting the dispersant including the electrically conductive particles over the metal layer, the insulating section and the interconnect pattern.

8. The method of manufacturing an electronic device as defined by claim 5,

wherein the insulating section is formed of a resin.

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9. The method of manufacturing an electronic device as defined by claim 6,

wherein the insulating section is formed of a resin.

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10. The method of manufacturing an electronic device as defined by claim 7,

wherein the insulating section is formed of a resin.

11. The method of manufacturing an electronic device as defined by claim 5,

wherein the insulating section is formed to have an inclined surface descending in an outward direction from the chip component.

12. The method of manufacturing an electronic device as defined by claim 6,
5 wherein the insulating section is formed to have an inclined surface descending in an outward direction from the chip component.

13. The method of manufacturing an electronic device as defined by claim 7,
10 wherein the insulating section is formed to have an inclined surface descending in an outward direction from the chip component.

14. The method of manufacturing an electronic device as defined by claim 8,
15 wherein the insulating section is formed to have an inclined surface descending in an outward direction from the chip component.

15. The method of manufacturing an electronic device as defined by claim 9,
wherein the insulating section is formed to have an inclined surface descending in an outward direction from the chip component.

20 16. The method of manufacturing an electronic device as defined by claim 10,
wherein the insulating section is formed to have an inclined surface descending in an outward direction from the chip component.

17. A circuit board on which the electronic device defined by claim 1 is mounted.

25 18. An electronic instrument having the electronic device defined by claim 1.